

# TENCON 2024 Singapore

The conference for IEEE Region 10 Members  
By Region 10, for Region 10

December 1-4, 2024

Organized by



# Conference Theme

## **Artificial Intelligence(AI) and Deep Learning Technologies for a Sustainable Future**

# Singapore Bay View





# IEEE Region 10 Conference 2024 (TENCON 2024)

Artificial Intelligence and Deep Learning Technologies for a Sustainable Future

1-4 December 2024 | Marina Bay Sands | Singapore

[www.tencon2024.org](http://www.tencon2024.org)

## ORGANIZING COMMITTEE

### Advisory Committee

Lance FUNG, Australia  
Deepak MATHUR, India

### General Chairs

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Michael ONG, Singapore Section

### Technical Program Co-Chairs

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## CALL FOR PAPERS

TENCON is a premier international technical conference of IEEE Region 10, which comprises 60 Sections, 6 Councils and 42 Sub-sections in the Asia Pacific regions. The theme for TENCON 2024 is Artificial Intelligence and Deep Learning Technologies for a Sustainable Future and it will be held in Singapore from December 1 – 4, 2024.

This conference is expected to bring together researchers, educators, students, practitioners, technocrats and policymakers from across academia, government, industry and non-governmental organizations to discuss, share and promote current works and recent accomplishments across all aspects of electrical, electronics and computer engineering, and information technology. Distinguished speakers will be invited to deliver keynote speeches and invited talks on trends and significant advances in the emerging technologies.

The online electronic paper submission will open from 1 March 2024. The scope of conference papers and exhibits include but not limited to the following areas:

### Publicity Chair

Aishwarya BANDLA, NUS Singapore

### Publication Chair

Bin LUO, IIR Singapore

### Special Sessions Chairs

Shilpa MANANDHAR, NMC Singapore

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### Sponsorship Chairs

Ravinder SINGH, Infineon Singapore

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### Local Logistic Chairs

Emily HAO, IIR Singapore

Chau YUEN, NTU Singapore

following areas:

- ✓ Artificial Intelligence and Machine Learning
- ✓ Data Analytics and Big Data
- ✓ Robotics, Control, Instrumentation and Automation
- ✓ Signal Processing and Image Recognition
- ✓ Computational Intelligence
- ✓ Network and Cyber-Security
- ✓ Communications and Networks
- ✓ RF/Millimeter-wave Circuits and Systems
- ✓ Antennas, Propagation and Computational EM
- ✓ Analog and Mixed Signal ICs
- ✓ Optical Communications and Sensors
- ✓ Photonic Technologies
- ✓ Internet of Things/MEMs Sensors
- ✓ Power Electronics
- ✓ Power Generation, Transmission and Distribution
- ✓ Electrical Motors and Drives
- ✓ Renewable Energy Sources and Technology
- ✓ Electronic Devices and Materials Processing
- ✓ Nano-electronics
- ✓ 3D Printing
- ✓ Quantum Technologies
- ✓ Education in Engineering and Technology
- ✓ Biomedical Engineering and Healthcare Technologies
- ✓ Sustainable Building and Environment Technologies

TENCON 2024 will feature both invited and contributed papers. The best papers will be selected from the contributed papers for awards. The presented papers will be submitted to IEEE Xplore which is indexed by major databases. Prospective authors are invited to **submit full papers** that are **three to four pages**, with **double column IEEE Conference format**.

## IMPORTANT DATES

**Paper Submission Deadline: 30 May 2024**

**Notice of Acceptance: 1 Aug 2024**

**Final Manuscripts Submission: 10 Sep 2024**

Organised by:



IEEE TENCON 2024 Secretariat c/o ace:daytons direct (int'l) pte ltd

Leng Kee Road #04-01 Thye Hong Centre Singapore 159086

tel: (65) 6379 5260 / 6379 5261 / email: secretariat@tencon2024.org

 [WWW.TENCON2024.ORG](http://WWW.TENCON2024.ORG)

For Abstract Submission,  
Scan the QR Code or visit



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# Arrangements

- First Call- for Papers: Nov 2023
- Final Call-for-Papers: March 2024
- Email reminders: April 2024

<b>Dates</b>	<b>Tentative Schedule</b>
<b>10 May 2024</b>	<b>Proposals for special sessions &amp; Proposals for workshops and tutorials</b>
<b>30 May 2024</b>	<b>Preliminary paper submissions (3-4 pages in PDF format comply with IEEEExplore)</b>
<b>1 August 2024</b>	<b>Notification of acceptance</b>
<b>10 Sep 2024</b>	<b>Final paper submissions</b>
<b>Dec 2024 (1-4)</b>	<b>TENCON 2024 Conference events</b>

# Preliminary Schedule/program

Dec 01 2024 – Parallel Tutorials (afternoon)  
- Welcome reception

Dec 02, 2024 morning– Opening ceremony followed by Keynote talks (3)  
  
afternoon – Oral sessions of multiple parallel tracks  
after the tea break – poster session

Dec 03, 2024 morning – oral sessions of parallel tracks and poster session  
Afternoon – Oral sessions of parallel tracks  
After the tea break – poster session  
  
Evening – Banquet dinner

Dec 04, 2024 morning and afternoon – Oral sessions of multiple parallel tracks  
and poster sessions

# Local Organising Committee Members

Prof. A. Alphones, Nanyang Technological University

Dr. Michael Ong, IEEE Singapore Section

Dr Sanjib Kumar Sahoo, National University of Singapore

Prof Lee Yee Hui, , Nanyang Technological University

Prof. Christopher HT Lee, , Nanyang Technological University

Dr Nicholas Wong, Singapore Institute of Technology

Dr Aishwarya Bandla, National University of Singapore

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Dr Shilpa Manandhar, National Meteorology Centre, Singapore

Dr Ravindar Singh, Infineon, Singapore

Dr Tan Yen Kheng, SIMTECH, ASTAR, Singapore

Dr Emily Hao, Institute for Infocomm Research, ASTAR, Singapore

Prof Yuen Chau, Nanyang Technological University, Singapore

All the above members have experience as General chairs/ committee members of IEEE conferences organized in Singapore by various societies in recent years, and successfully organized all events and active in IEEE.



# Technical Plans

- All papers will be published in electronic format proceedings in thumb drive comply with IEEExplore.
- Working language in conference and publications will be in English.
- The technical areas or topics of the conference have wide scope of electrical, electronics and information domain leading to AI in human care and sustainable future.
- Also, Welcome reception, banquet, and social tours will be planned during the conference period.

# See you at TENCON 2024 in Singapore

- The organization committee welcomes everyone for stronger participation and continued support

Discover a world of unique contrasts

